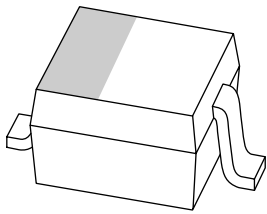


# DATA SHEET



## **PDZ-B series** Voltage regulator diodes

Product data sheet  
Supersedes data of 2002 Feb 18

2004 Mar 22

# Voltage regulator diodes

# PDZ-B series

### FEATURES

- Total power dissipation: max. 400 mW
- Small plastic package suitable for surface mounted design
- Wide variety of voltage ranges: nominal 2.4 to 36 V (E24 range)
- Tolerance approximately  $\pm 2\%$ .

### APPLICATIONS

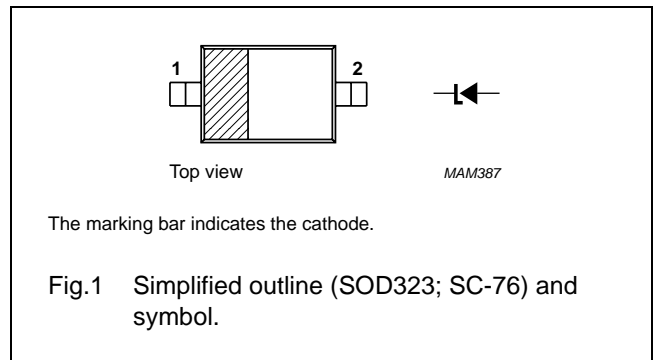
- General voltage regulation.

### DESCRIPTION

Low-power general purpose voltage regulator diodes in a small plastic SMD SOD323 (SC-76) package.

### PINNING

PIN	DESCRIPTION
1	cathode
2	anode



### MARKING

TYPE NUMBER	MARKING CODE	TYPE NUMBER	MARKING CODE	TYPE NUMBER	MARKING CODE	TYPE NUMBER	MARKING CODE
PDZ2.4B	Z0	PDZ5.1B	Z8	PDZ11B	ZG	PDZ24B	ZQ
PDZ2.7B	Z1	PDZ5.6B	Z9	PDZ12B	ZH	PDZ27B	ZR
PDZ3.0B	Z2	PDZ6.2B	ZA	PDZ13B	ZJ	PDZ30B	ZS
PDZ3.3B	Z3	PDZ6.8B	ZB	PDZ15B	ZK	PDZ33B	ZT
PDZ3.6B	Z4	PDZ7.5B	ZC	PDZ16B	ZL	PDZ36B	ZU
PDZ3.9B	Z5	PDZ8.2B	ZD	PDZ18B	ZM		
PDZ4.3B	Z6	PDZ9.1B	ZE	PDZ20B	ZN		
PDZ4.7B	Z7	PDZ10B	ZF	PDZ22B	ZP		

### ORDERING INFORMATION

TYPE NUMBER	PACKAGE		
	NAME	DESCRIPTION	VERSION
PDZ2.4B to PDZ36B	-	plastic surface mounted package; 2 leads	SOD323

## Voltage regulator diodes

## PDZ-B series

**LIMITING VALUES**

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
$I_F$	continuous forward current		–	200	mA
$I_{ZSM}$	non-repetitive peak reverse current	$t_p = 100 \mu\text{s}$ ; square wave; $T_{\text{amb}} = 25 \text{ }^\circ\text{C}$ prior to surge	see Table 2		
$P_{\text{tot}}$	total power dissipation	$T_{\text{amb}} = 25 \text{ }^\circ\text{C}$ ; note 1; see Fig.2	–	400	mW
$T_{\text{stg}}$	storage temperature		–65	+150	$^\circ\text{C}$
$T_j$	junction temperature		–	150	$^\circ\text{C}$

**Note**

1. Device mounted on a printed-circuit board measuring  $11 \times 25 \times 1.6 \text{ mm}$ .

**THERMAL CHARACTERISTICS**

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
$R_{\text{th}(j-s)}$	thermal resistance from junction to soldering point		130	K/W
$R_{\text{th}(j-a)}$	thermal resistance from junction to ambient	note 1	340	K/W

**Note**

1. Device mounted on a printed-circuit board measuring  $11 \times 25 \times 1.6 \text{ mm}$ .

## Voltage regulator diodes

## PDZ-B series

## CHARACTERISTICS

Table 1 Total series

 $T_j = 25\text{ }^\circ\text{C}$  unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MAX.	UNIT
$V_F$	forward voltage	$I_F = 10\text{ mA}$ ; see Fig.3	0.9	V
		$I_F = 100\text{ mA}$ ; see Fig.3	1.1	V
$I_R$	reverse current			
	PDZ2.4B	$V_R = 1\text{ V}$	50	$\mu\text{A}$
	PDZ2.7B	$V_R = 1\text{ V}$	20	$\mu\text{A}$
	PDZ3.0B	$V_R = 1\text{ V}$	10	$\mu\text{A}$
	PDZ3.3B	$V_R = 1\text{ V}$	5	$\mu\text{A}$
	PDZ3.6B	$V_R = 1\text{ V}$	5	$\mu\text{A}$
	PDZ3.9B	$V_R = 1\text{ V}$	3	$\mu\text{A}$
	PDZ4.3B	$V_R = 1\text{ V}$	3	$\mu\text{A}$
	PDZ4.7B	$V_R = 1\text{ V}$	2	$\mu\text{A}$
	PDZ5.1B	$V_R = 1.5\text{ V}$	2	$\mu\text{A}$
	PDZ5.6B	$V_R = 2.5\text{ V}$	1	$\mu\text{A}$
	PDZ6.2B	$V_R = 3\text{ V}$	500	nA
	PDZ6.8B	$V_R = 3.5\text{ V}$	500	nA
	PDZ7.5B	$V_R = 4\text{ V}$	500	nA
	PDZ8.2B	$V_R = 5\text{ V}$	500	nA
	PDZ9.1B	$V_R = 6\text{ V}$	500	nA
	PDZ10B	$V_R = 7\text{ V}$	100	nA
	PDZ11B	$V_R = 8\text{ V}$	100	nA
	PDZ12B	$V_R = 9\text{ V}$	100	nA
	PDZ13B	$V_R = 10\text{ V}$	100	nA
	PDZ15B	$V_R = 11\text{ V}$	50	nA
	PDZ16B	$V_R = 12\text{ V}$	50	nA
	PDZ18B	$V_R = 13\text{ V}$	50	nA
PDZ20B	$V_R = 15\text{ V}$	50	nA	
PDZ22B	$V_R = 17\text{ V}$	50	nA	
PDZ24B	$V_R = 19\text{ V}$	50	nA	
PDZ27B	$V_R = 21\text{ V}$	50	nA	
PDZ30B	$V_R = 23\text{ V}$	50	nA	
PDZ33B	$V_R = 25\text{ V}$	50	nA	
PDZ36B	$V_R = 27\text{ V}$	50	nA	

## Voltage regulator diodes

## PDZ-B series

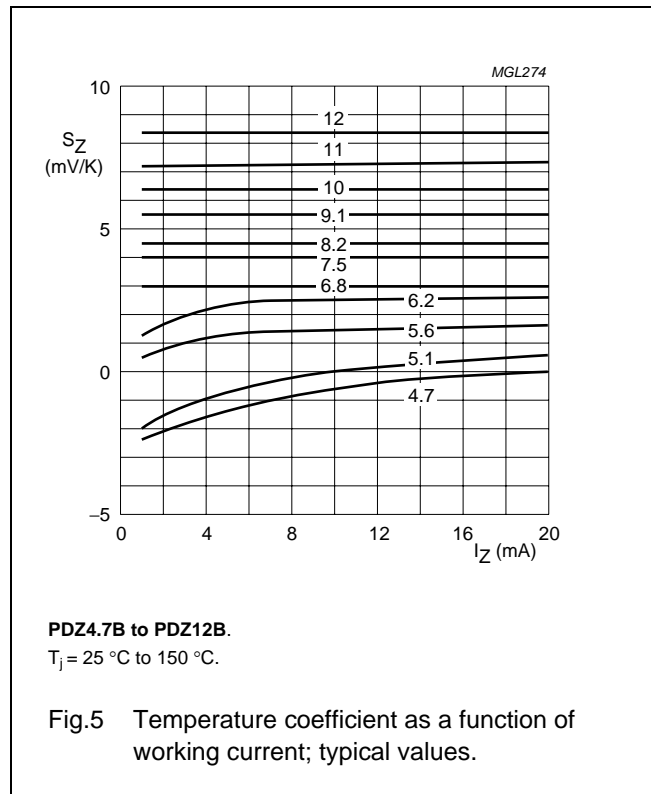
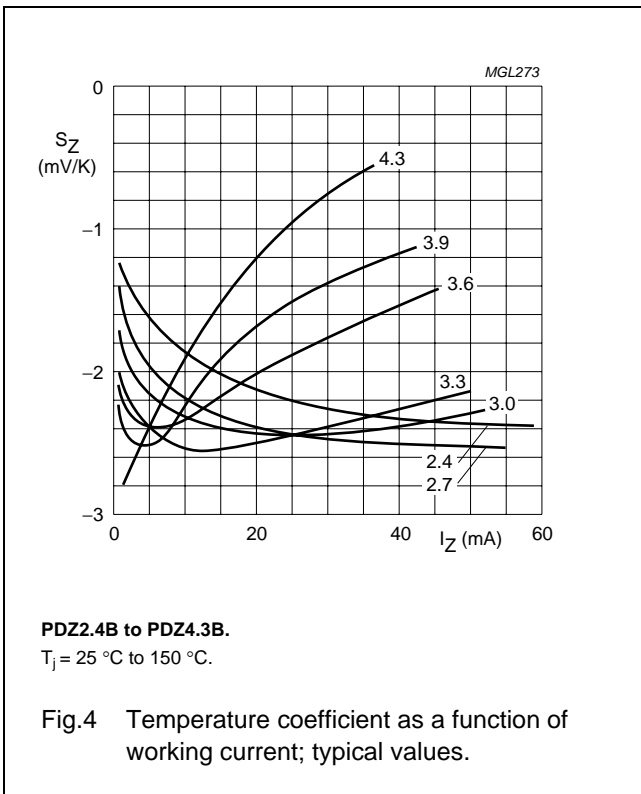
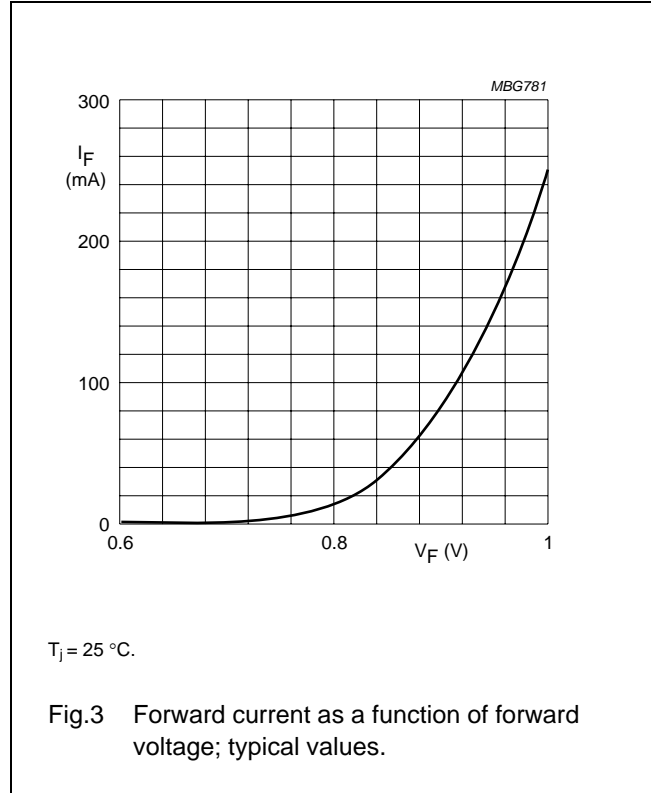
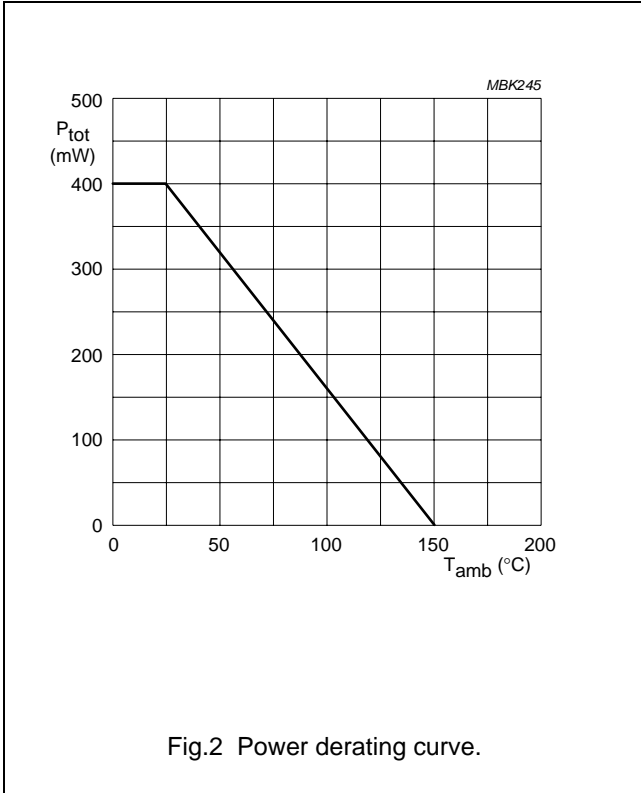
**Table 2** Per type $T_j = 25\text{ °C}$  unless otherwise specified.

TYPE NUMBER	WORKING VOLTAGE $V_z$ (V) at $I_z = 5\text{ mA}$		DIFFERENTIAL RESISTANCE $r_{dif}$ ( $\Omega$ )				TEMP. COEFF. $S_z$ (mV/K) at $I_z = 5\text{ mA}$ (see Figs 4 and 5)	DIODE CAP. $C_d$ (pF) at $f = 1\text{ MHz}$ ; $V_R = 0$	NON-REPETITIVE PEAK REVERSE CURRENT $I_{zSM}$ (A) at $t_p = 100\text{ }\mu\text{s}$ ; $T_{amb} = 25\text{ °C}$
	MIN.	MAX.	MAX.	at $I_z$ (mA)	MAX.	at $I_z$ (mA)	TYP.	MAX.	MAX.
PDZ2.4B	2.43	2.63	1000	0.5	100	5	-1.6	450	8.0
PDZ2.7B	2.69	2.91	1000	0.5	100	5	-2.0	440	8.0
PDZ3.0B	2.85	3.07	1000	0.5	95	5	-2.1	425	8.0
PDZ3.3B	3.32	3.53	1000	0.5	95	5	-2.4	410	8.0
PDZ3.6B	3.60	3.85	500	1.0	90	5	-2.4	390	8.0
PDZ3.9B	3.89	4.16	500	1.0	90	5	-2.5	370	8.0
PDZ4.3B	4.17	4.48	600	1.0	90	5	-2.5	350	8.0
PDZ4.7B	4.55	4.75	600	1.0	90	5	-1.4	325	8.0
PDZ5.1B	4.96	5.20	250	0.5	60	5	0.3	300	5.5
PDZ5.6B	5.48	5.73	100	0.5	50	5	1.9	275	5.5
PDZ6.2B	6.06	6.33	80	0.5	50	5	2.7	250	5.5
PDZ6.8B	6.65	6.93	60	0.5	40	5	3.4	215	5.5
PDZ7.5B	7.28	7.60	60	0.5	10	5	4.0	170	3.5
PDZ8.2B	8.02	8.36	60	0.5	10	5	4.6	150	3.5
PDZ9.1B	8.85	9.23	60	0.5	10	5	5.5	120	3.5
PDZ10B	9.77	10.21	60	0.5	10	5	6.4	110	3.5
PDZ11B	10.78	11.22	60	0.5	10	5	7.4	108	3.0
PDZ12B	11.74	12.24	80	0.5	10	5	8.4	105	3.0
PDZ13B	12.91	13.49	80	0.5	10	5	9.4	103	2.5
PDZ15B	14.34	14.98	80	0.5	15	5	11.4	99	2.0
PDZ16B	15.85	16.51	80	0.5	20	5	12.4	97	1.5
PDZ18B	17.56	18.35	80	0.5	20	5	14.4	93	1.5
PDZ20B	19.52	20.39	100	0.5	20	5	16.4	88	1.5
PDZ22B	21.54	22.47	100	0.5	25	5	18.4	84	1.3
PDZ24B	23.72	24.78	120	0.5	30	5	20.4	80	1.3
PDZ27B	26.19	27.53	150	0.5	40	5	23.4	73	1.0
PDZ30B	29.19	30.69	200	0.5	40	5	26.6	66	1.0
PDZ33B	32.15	33.79	250	0.5	40	5	29.7	60	0.9
PDZ36B	35.07	36.87	300	0.5	60	5	33.0	59	0.8

Voltage regulator diodes

PDZ-B series

GRAPHICAL DATA



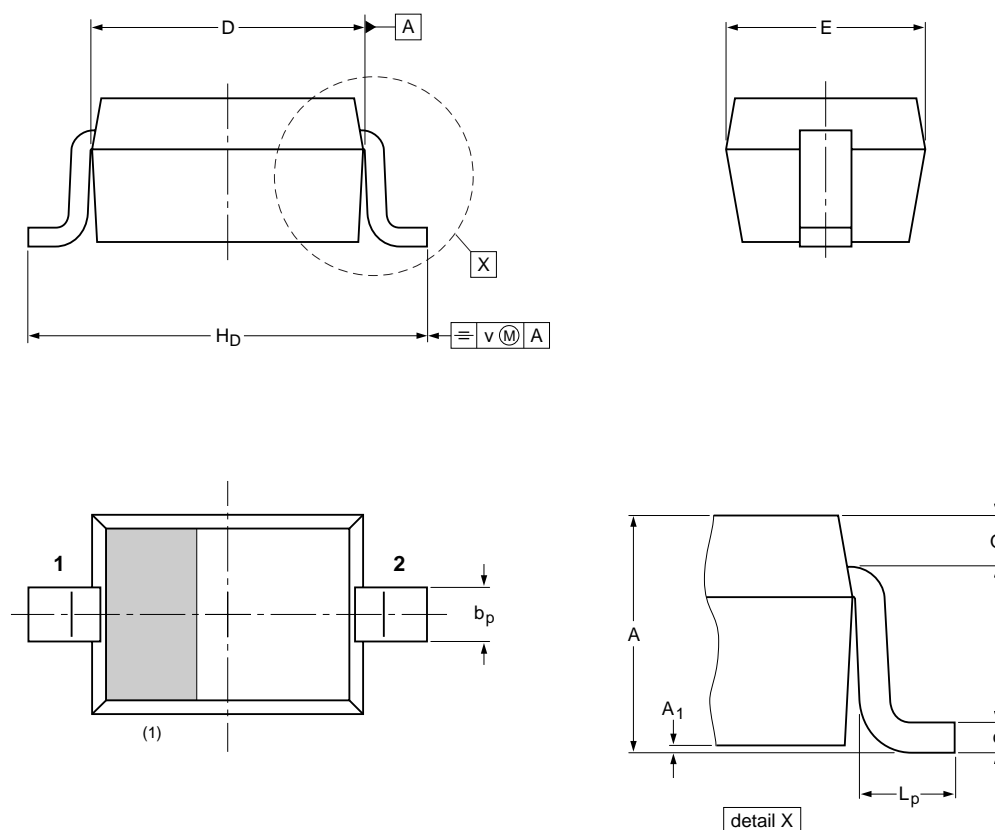
Voltage regulator diodes

PDZ-B series

PACKAGE OUTLINE

Plastic surface-mounted package; 2 leads

SOD323



DIMENSIONS (mm are the original dimensions)

UNIT	A	A <sub>1</sub> max	b <sub>p</sub>	c	D	E	H <sub>D</sub>	L <sub>p</sub>	Q	v
mm	1.1 0.8	0.05	0.40 0.25	0.25 0.10	1.8 1.6	1.35 1.15	2.7 2.3	0.45 0.15	0.25 0.15	0.2

Note

1. The marking bar indicates the cathode

OUTLINE VERSION	REFERENCES			EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA		
SOD323			SC-76		-03-12-17- 06-03-16

## Voltage regulator diodes

## PDZ-B series

## DATA SHEET STATUS

DOCUMENT STATUS <sup>(1)</sup>	PRODUCT STATUS <sup>(2)</sup>	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

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## **Contact information**

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